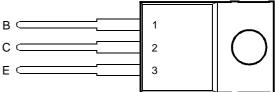
- Designed for Complementary Use with BDX33, BDX33A, BDX33B, BDX33C and BDX33D
- 70 W at 25°C Case Temperature
- 10 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 3 A

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	BDX34		-45	
Collector-base voltage (I _E = 0)	BDX34A		-60	
	BDX34B	V _{CBO}	-80	V
	BDX34C		-100	
	BDX34D		-120	
	BDX34		-45	
Collector-emitter voltage (I _B = 0)	BDX34A		-60	
	BDX34B	V _{CEO}	-80	V
	BDX34C		-100	
	BDX34D		-120	
Emitter-base voltage	V _{EBO}	-5	V	
Continuous collector current	I _C	-10	Α	
Continuous base current	I _B	-0.3	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 1)	P _{tot}	70	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note	P _{tot}	2	W	
Operating free air temperature range	T _J	-65 to +150	°C	
Storage temperature range	T _{stg}	-65 to +150	°C	
Operating free-air temperature range	T _A	-65 to +150	°C	

NOTES: 1. Derate linearly to 150°C case temperature at the rate of 0.56 W/°C.

2. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.

BDX34, BDX34A, BDX34B, BDX34C, BDX34D PNP SILICON POWER DARLINGTONS

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electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
					BDX34	-45			
V _{(BR)CEO}	Collector-emitter breakdown voltage		I _B = 0 (see Note 3)		BDX34A	-60			
		I _C = -100 mA		(see Note 3)	BDX34B	-80			V
					BDX34C	-100			
					BDX34D	-120			
	Collector-emitter	V _{CE} = -30 V	I _B = 0		BDX34			-0.5	
		$V_{CE} = -30 \text{ V}$	$I_B = 0$		BDX34A			-0.5	
,		$V_{CE} = -40 \text{ V}$	$I_B = 0$		BDX34B			-0.5	
		$V_{CE} = -50 \text{ V}$	$I_B = 0$		BDX34C			-0.5	m Λ
		$V_{CE} = -60 \text{ V}$	$I_B = 0$		BDX34D			-0.5	
I _{CEO}	cut-off current	$V_{CE} = -30 \text{ V}$	$I_B = 0$	$T_C = 100$ °C	BDX34			-10	mA
		$V_{CE} = -30 \text{ V}$	$I_B = 0$	$T_C = 100$ °C	BDX34A			-10	
		$V_{CE} = -40 \text{ V}$	$I_B = 0$	$T_C = 100$ °C	BDX34B			-10	
		$V_{CE} = -50 \text{ V}$	$I_B = 0$	$T_C = 100$ °C	BDX34C			-10	
		V _{CE} = -60 V	$I_B = 0$	$T_C = 100$ °C	BDX34D			-10	
		V _{CB} = -45 V	I _E = 0		BDX34			-1	
		$V_{CB} = -60 \text{ V}$	$I_E = 0$		BDX34A			-1	
		$V_{CB} = -80 \text{ V}$	$I_E = 0$		BDX34B			-1	mA
		$V_{CB} = -100 \text{ V}$	$I_E = 0$		BDX34C			-1	
1	Collector cut-off	$V_{CB} = -120 \text{ V}$	$I_E = 0$		BDX34D			-1	
I _{CBO}	current	$V_{CB} = -45 \text{ V}$	$I_E = 0$	$T_C = 100$ °C	BDX34			-5	
		$V_{CB} = -60 \text{ V}$	$I_E = 0$	$T_C = 100$ °C	BDX34A			-5	
		$V_{CB} = -80 \text{ V}$	$I_E = 0$	$T_C = 100$ °C	BDX34B			-5	
		$V_{CB} = -100 \text{ V}$	$I_E = 0$	$T_C = 100$ °C	BDX34C			-5	
		$V_{CB} = -120 \text{ V}$	$I_E = 0$	$T_C = 100$ °C	BDX34D			-5	
I _{EBO}	Emitter cut-off current	V _{EB} = -5 V	I _C = 0					-10	mA
	Forward current transfer ratio	V _{CE} = -3 V	I _C = -4 A		BDX34	750			
		V _{CE} = -3 V	$I_C = -4 A$		BDX34A	750			
h_{FE}		V _{CE} = -3 V	$I_C = -3 A$	(see Notes 3 and 4)	BDX34B	750			
		V _{CE} = -3 V	$I_C = -3 A$		BDX34C	750			
		V _{CE} = -3 V	$I_C = -3 A$		BDX34D	750			
	Base-emitter voltage	V _{CE} = -3 V	I _C = -4 A		BDX34			-2.5	
		V _{CE} = -3 V	$I_C = -4 A$		BDX34A			-2.5	
$V_{BE(on)}$		V _{CE} = -3 V	$I_C = -3 A$	(see Notes 3 and 4)	BDX34B			-2.5	V
		V _{CE} = -3 V	$I_C = -3 A$		BDX34C			-2.5	
		V _{CE} = -3 V	$I_C = -3 A$		BDX34D			-2.5	
V _{CE(sat)}	Collector-emitter saturation voltage	I _B = -8 mA	I _C = -4 A		BDX34			-2.5	
		$I_B = -8 \text{ mA}$	$I_C = -4 A$		BDX34A			-2.5	
		$I_B = -6 \text{ mA}$	$I_C = -3 A$	(see Notes 3 and 4)	BDX34B			-2.5	V
		$I_B = -6 \text{ mA}$	$I_C = -3 A$		BDX34C			-2.5	
		$I_B = -6 \text{ mA}$	$I_C = -3 A$		BDX34D			-2.5	
V _{EC}	Parallel diode forward voltage	I _E = -8 A	I _B = 0					-4	V

NOTES: 3. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

^{4.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

BDX34, BDX34A, BDX34B, BDX34C, BDX34D PNP SILICON POWER DARLINGTONS

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thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.78	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

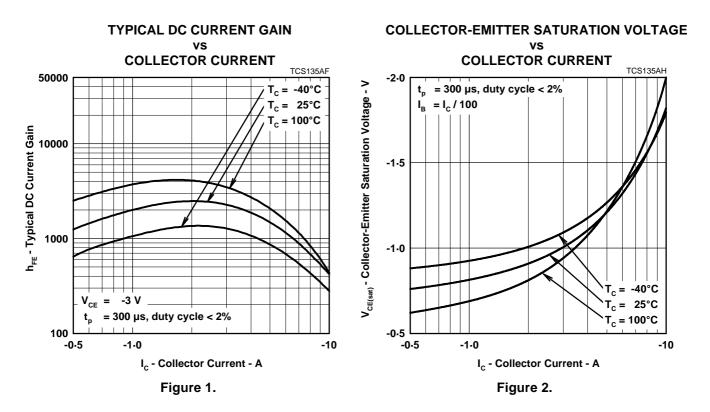
resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t _{on}	Turn-on time	I _C = -3 A	$I_{B(on)} = -12 \text{ mA}$	$I_{B(off)} = 12 \text{ mA}$		1		μs
t _{off}	Turn-off time	$V_{BE(off)} = 3.5 \text{ V}$	$R_L = 10 \Omega$	t_p = 20 μ s, dc \leq 2%		5		μs

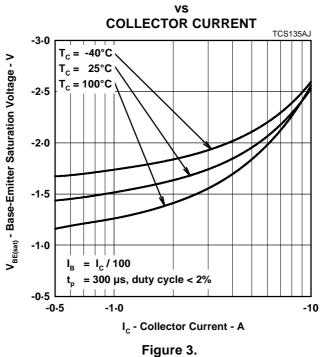
[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.



TYPICAL CHARACTERISTICS



BASE-EMITTER SATURATION VOLTAGE



PRODUCT INFORMATION

THERMAL INFORMATION

MAXIMUM POWER DISSIPATION

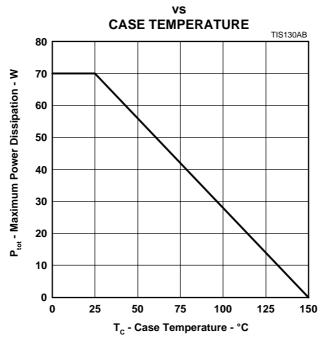


Figure 4.

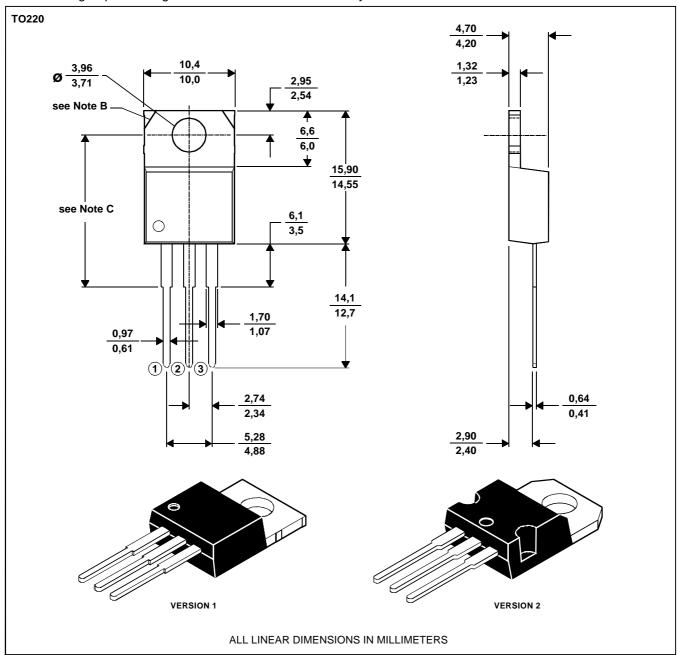
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. **MDXXBE**

PRODUCT INFORMATION

BDX34, BDX34A, BDX34B, BDX34C, BDX34D PNP SILICON POWER DARLINGTONS

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